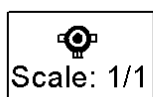
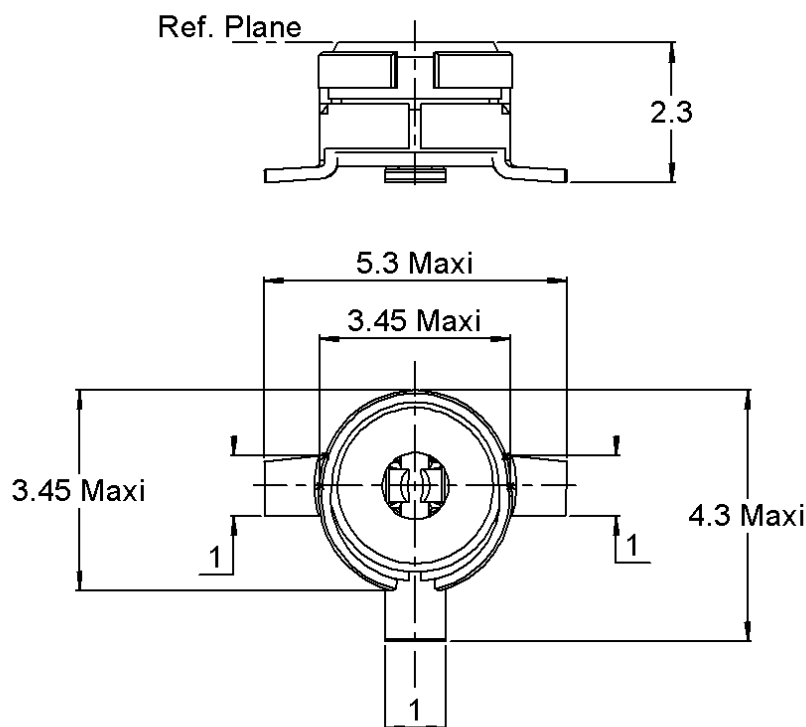


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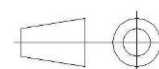
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All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
Body	PHOSPHOR BRONZE	GOLD 0.2 OVER NICKEL 2
Center contact	BERYLLIUM COPPER	GOLD 0.2 OVER TIN NICKEL 2
Outer contact		
Insulator	PTFE	
Gasket	-	-
Others parts	-	-
-	-	-
-	-	-

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PACKAGING

Standard	Unit	Other
3000	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	0-6	GHz
VSWR	* + 0,0000	x F(GHz) Maxi
Insertion loss	**	$\sqrt{F}$ (GHz) dB Maxi
RF leakage	- (NA	- F(GHz)) dB Maxi
Voltage rating	50	Veff Maxi
Dielectric withstanding voltage	250	Veff mini
Insulation resistance	500	M Ω mini

ENVIRONMENTAL

Operating temperature	-40/+125	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	NA	N mini
Axial force – Opposite end	NA	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	50	Cycles mini
Weight	0,0590	g

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

***1.2 à 2GHz/Avg 1,07 **Max 0.07/Avg 0.06**

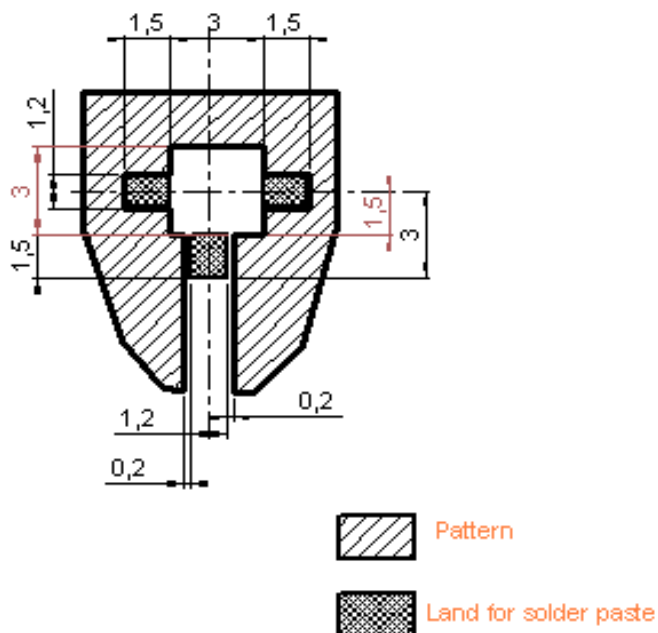
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MMS SERIES – INFORMATION

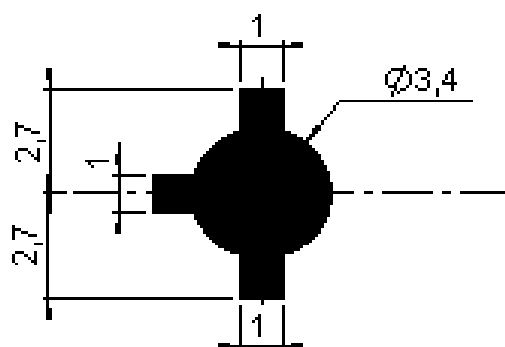
Coplanar line : Ground and signal are on the same side . Thickness of PCB : 1mm

The material of PCB is glass-epoxy composite. ($\epsilon_r = 4.8$)

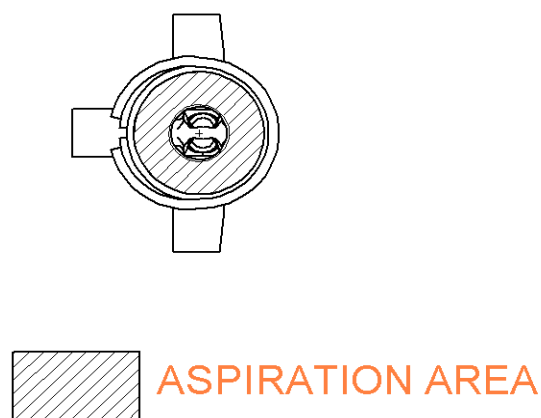
The solder resist should be printed except for the land pattern on the PCB.



SHADOW OF MMS RECEPTACLE FOR VIDEO CAMERA



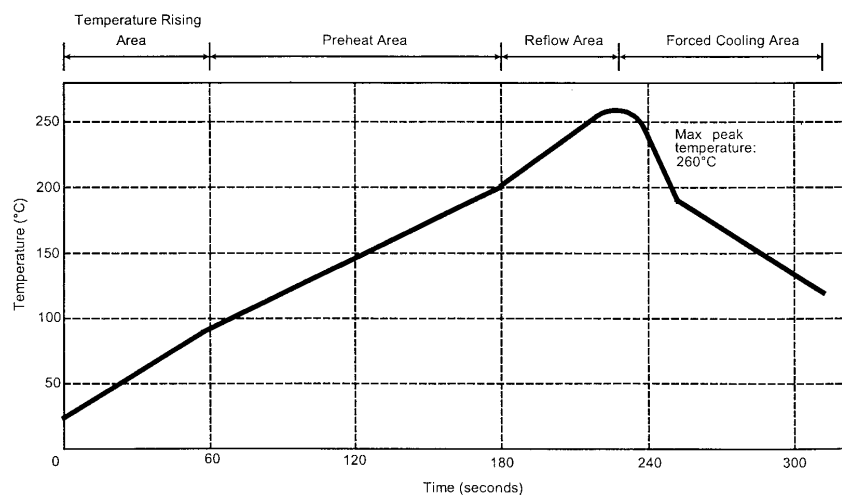
ASPIRATION AREA



SOLDER PROCEDURE

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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